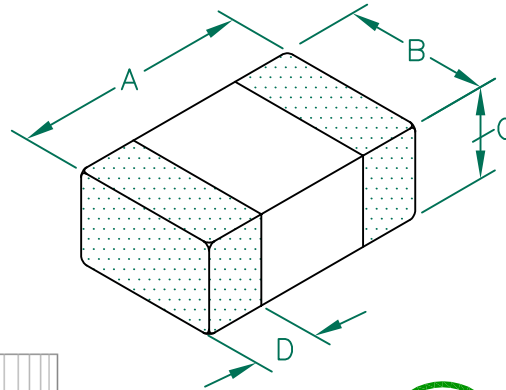


CPI0805G1R5R-10

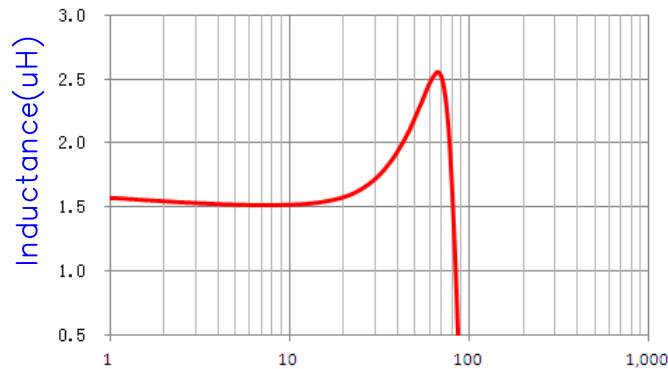
**UNCONTROLLED
DOCUMENT**

PHYSICAL DIMENSIONS:

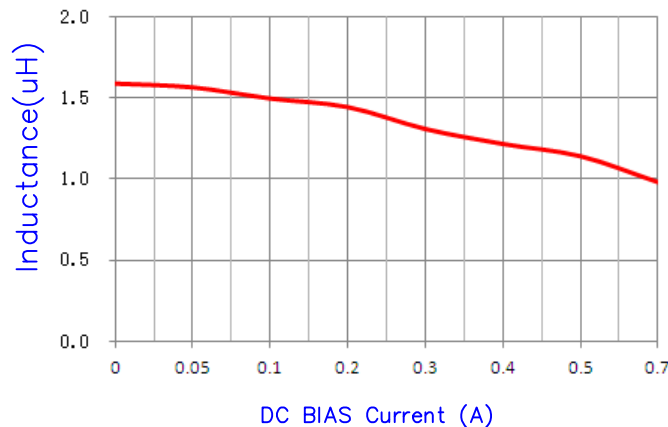
A	2.00 [.079]	+ 0.20[.008]
B	1.25 [.049]	+ 0.20[.008]
C	0.90 [.035]	+ 0.10[.004]
D	0.50 [.020]	+ 0.20[.008]



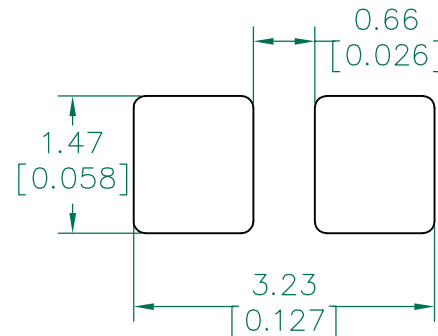
Ls vs Frequency



Ls vs DC BIAS Current



LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763 [0.030] to this dimension)

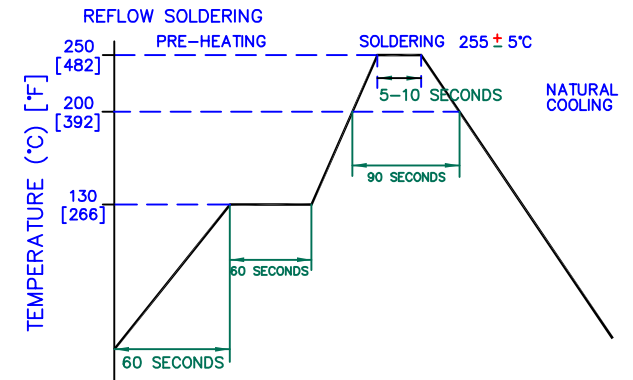
ELECTRICAL CHARACTERISTICS:

	L (μH) @ 1MHz ± 20%	DCR (Ω) ± 25%	I (Max)
Nom	1.5	0.22	
Min	1.2	0.165	
Max	1.8	0.275	700mA

NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
5. Operation Temperature TEMP: -55°C~+125°C. (INCLUDING SELF-HEATING)

RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES]				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.			
C	CHANGE PLASTIC TAPE TO PAPER TAPE	04/17/14	QU	PROJECT/PART NUMBER: CPI0805G1R5R-10			
B	UPDATE LAIRD LOGO AND NOTES 5	08/05/13	QU	DATE: 03/01/11	SCALE: NTS	SHEET: 1 of 1	
A	ORIGINAL DRAFT	03/01/11	QU	CAD #	TOOL #		
REV	DESCRIPTION	DATE	INT	CPI0805G1R5R-10-A			